



KONTAKT

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Microtronic GmbH to Show Sonix ECHO™ Scanning Acoustic Microscope at SMT Hybrid Packaging

Munich, Germany — April 2017 — Microtronic GmbH, a leading sales specialist of microelectronics, today announced plans to show the Sonix ECHO™ scanning acoustic microscope in Stand 221j in Hall 5 at SMT Hybrid Packaging, scheduled to take place May 16-18, 2017 in Nuremberg, Germany. The ECHO™ enables package inspection of stacked dies, complex flip chips and more traditional plastic packages.

The ECHO VS adds industry-leading features for the clearest imaging of Cu pillars, molded flip chip (MUF), CSP, MCM, stacked die, hybrids, and other advanced package inspection applications. The ECHO Pro adds fully automated handling for 100 percent package inspection in high-volume production environments.

Ernst J. M. Eggelaar, President of Microtronic commented, “We are excited to present the latest developments and features of the Sonix ECHO to our customers. The system offers many new and cutting-edge features.”



For more information about Microtronic or to schedule a demonstration, visit www.microtronic.de.

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About Microtronic

Microtronic was founded in 1981 and is based near Munich, Germany. With 30 years' experience, we are the microelectronics leaders in Europe and offer a wide range of products and services to the microelectronics industries. We run regular training courses on various topics through in-house training or can arrange for specific employee training courses on request to suit your needs.

Our customers include companies who require added solderability test, ultrasonic microscopes, circuit board repair systems, welding systems, solders and solder pastes. We offer centralised pricing to our



customers with the added benefit of unparalleled delivery times from our centralized European warehouses.

For more information, please visit www.microtronic.de.